



NEC's L-BAND 4W HIGH POWER SPDT SWITCH IC

UPG2027TQ

FEATURES

- **LOW INSERTION LOSS:**
0.40 dB TYP. @ 1.0 GHz
0.50 dB TYP. @ 2.0 GHz
- **HIGH LINEARITY:**
 $2f_0, 3f_0 = 70 \text{ dBc TYP.}$ @ 1.0 GHz, $P_{in} = +35 \text{ dBm}$
 $2f_0, 3f_0 = 70 \text{ dBc TYP.}$ @ 2.0 GHz, $P_{in} = +33 \text{ dBm}$
- **HIGH-DENSITY SURFACE MOUNTING:**
10-pin plastic TSON package (2.30 × 2.55 × 0.60 mm)
- **Pb FREE**

DESCRIPTION

NEC's UPG2027TQ is a high power SPDT GaAs Switch IC for digital cellular and cordless telephone applications. This device can operate from 500 MHz to above 2.0 GHz, with low insertion loss and high linearity.

APPLICATIONS

- **GSM Triple / Quad Band Cellular**
- **Cordless Phones**
- **Short Range Wireless**

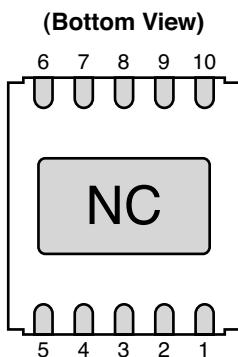
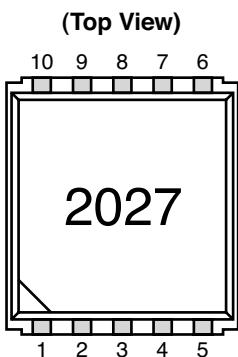
ORDERING INFORMATION

PART NUMBER	PACKAGE	MARKING	SUPPLYING FORM
UPG2027TQ-E1-A	10-pin plastic TSON	2027	<ul style="list-style-type: none"> • Embossed tape 8 mm wide • Pins 5, 6 face the perforation side of the tape • Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: UPG2027TQ-A

California Eastern Laboratories

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM

PIN NO.	PIN NAME
1	V_{cont2}
2	NC (GND)
3	Common
4	NC (GND)
5	V_{cont1}
6	RF1
7	NC (GND)
8	NC (GND)
9	NC (GND)
10	RF2

ABSOLUTE MAXIMUM RATINGS ($T_A = +25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	RATINGS		UNIT
Control Voltage	V_{cont}	+8.0		V
Input Power	P_{in}	+38		dBm
Operating Ambient Temperature	T_A	-45 to +85		°C
Storage Temperature	T_{stg}	-55 to +150		°C

RECOMMENDED OPERATING RANGE ($T_A = +25^\circ\text{C}$)

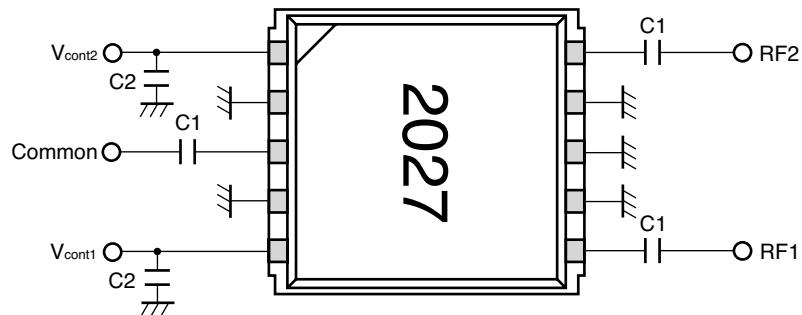
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Control Voltage (High)	$V_{cont(H)}$	+2.5	+2.7	+5.0	V
Control Voltage (Low)	$V_{cont(L)}$	0	0	+0.2	V

ELECTRICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$, $V_{\text{cont}} = +2.5 \text{ V}/0 \text{ V}$, $Z_0 = 50 \Omega$, DC blocking capacitors value: 56 pF, Each port, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Insertion Loss	L_{INS}	$f = 0.5 \text{ to } 1.0 \text{ GHz}$	-	0.40	0.65	dB
		$f = 1.0 \text{ to } 2.0 \text{ GHz}$	-	0.50	0.75	dB
Isolation	ISL	$f = 0.5 \text{ to } 1.0 \text{ GHz}$	23	25	-	dB
		$f = 1.0 \text{ to } 2.0 \text{ GHz}$	17	18.5	-	dB
2nd Harmonics	$2f_0$	$f = 1.0 \text{ GHz}, P_{\text{in}} = +35 \text{ dBm}$	65	70	-	dBc
		$f = 2.0 \text{ GHz}, P_{\text{in}} = +33 \text{ dBm}$	65	70	-	dBc
3rd Harmonics	$3f_0$	$f = 1.0 \text{ GHz}, P_{\text{in}} = +35 \text{ dBm}$	65	70	-	dBc
		$f = 2.0 \text{ GHz}, P_{\text{in}} = +33 \text{ dBm}$	65	70	-	dBc
Switching Speed	t_{sw}		-	1	5	μs
Control Current	I_{cont}	No RF	-	-	50	μA

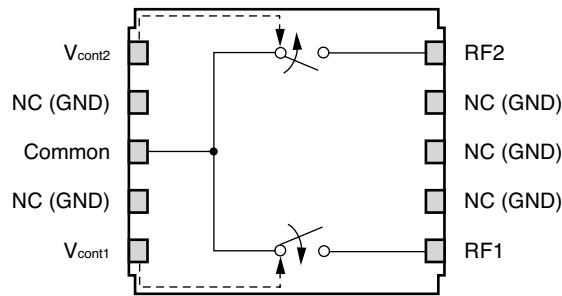
EVALUATION CIRCUIT

Off chip DC blocking capacitors value $C_1 = 56 \text{ pF}$, $C_2 = 1 \text{ 000 pF}$ (Bypass), using NEC standard evaluation board.

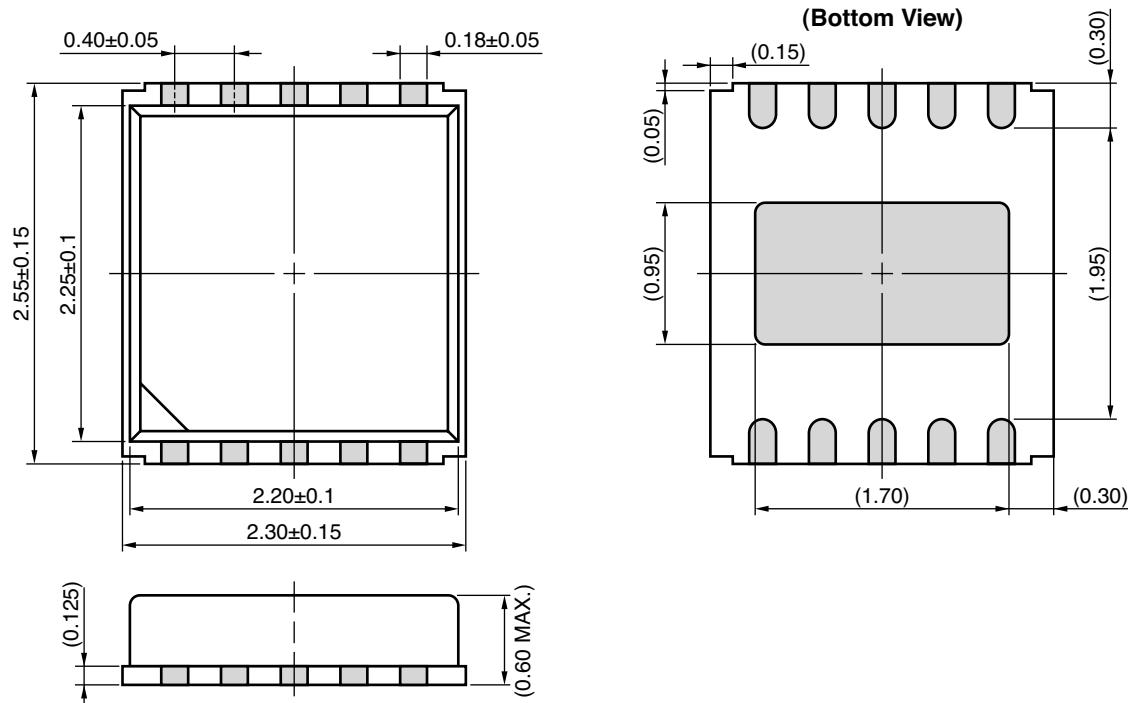


The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

TRUTH TABLE



V _{CONT1}	V _{CONT2}	COMMON-RF1	COMMON-RF2
High	Low	ON	OFF
Low	High	OFF	ON

PACKAGE DIMENSIONS**10-PIN PLASTIC TSON (UNIT:mm)**

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) Time at temperature of 200°C or higher Preheating time at 120 to 150°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 215°C or below : 25 to 40 seconds : 30 to 60 seconds : 3 times : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

Life Support Applications

These NEC products are not intended for use in life support devices, appliances, or systems where the malfunction of these products can reasonably be expected to result in personal injury. The customers of CEL using or selling these products for use in such applications do so at their own risk and agree to fully indemnify CEL for all damages resulting from such improper use or sale.

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11/12/2004

NEC

A Business Partner of NEC Compound Semiconductor Devices, Ltd.

Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix -A indicates that the device is Pb-free. The -AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
Lead (Pb)	< 1000 PPM	-A	-AZ
		Not Detected	(*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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